HANDLER FOR SEMICONDUCTOR SINGULATION AND METHOD THEREFOR

ABSTRACT

A water jet handler (200) has a loading location (205), a cutting location (210), and an unloading location (215); and two movable mounts (240 and 245). As a first movable mount (240) receives a molded substrate at the loading location (205), and transports it to the cutting location (210), a second movable mount (245) transports singulated semiconductor packages of a previously singulated molded substrate from the cutting location (210) to the unloading location (215). As the molded substrate on the first movable mount (240) is cut in the X direction (232) by a water jet, the singulated semiconductor packages are unloaded. The molded substrate is then transferred to the second movable mount (245) on which it is cut in the Y direction (272) to produce singulated semiconductor packages, as the first movable mount (240) returns to the loading location (205), where another molded substrate is loaded.

FIG. 2 accompanies the abstract.

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